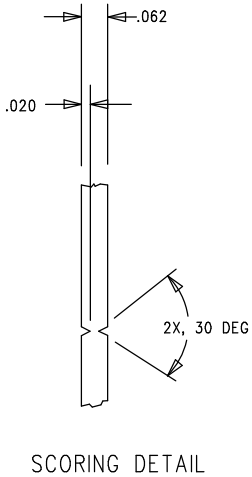
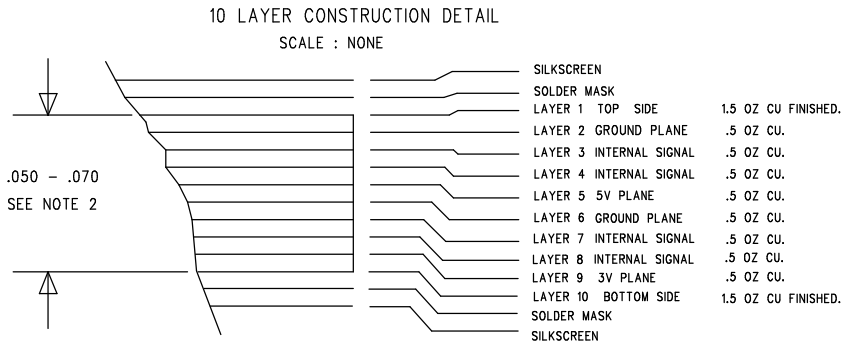
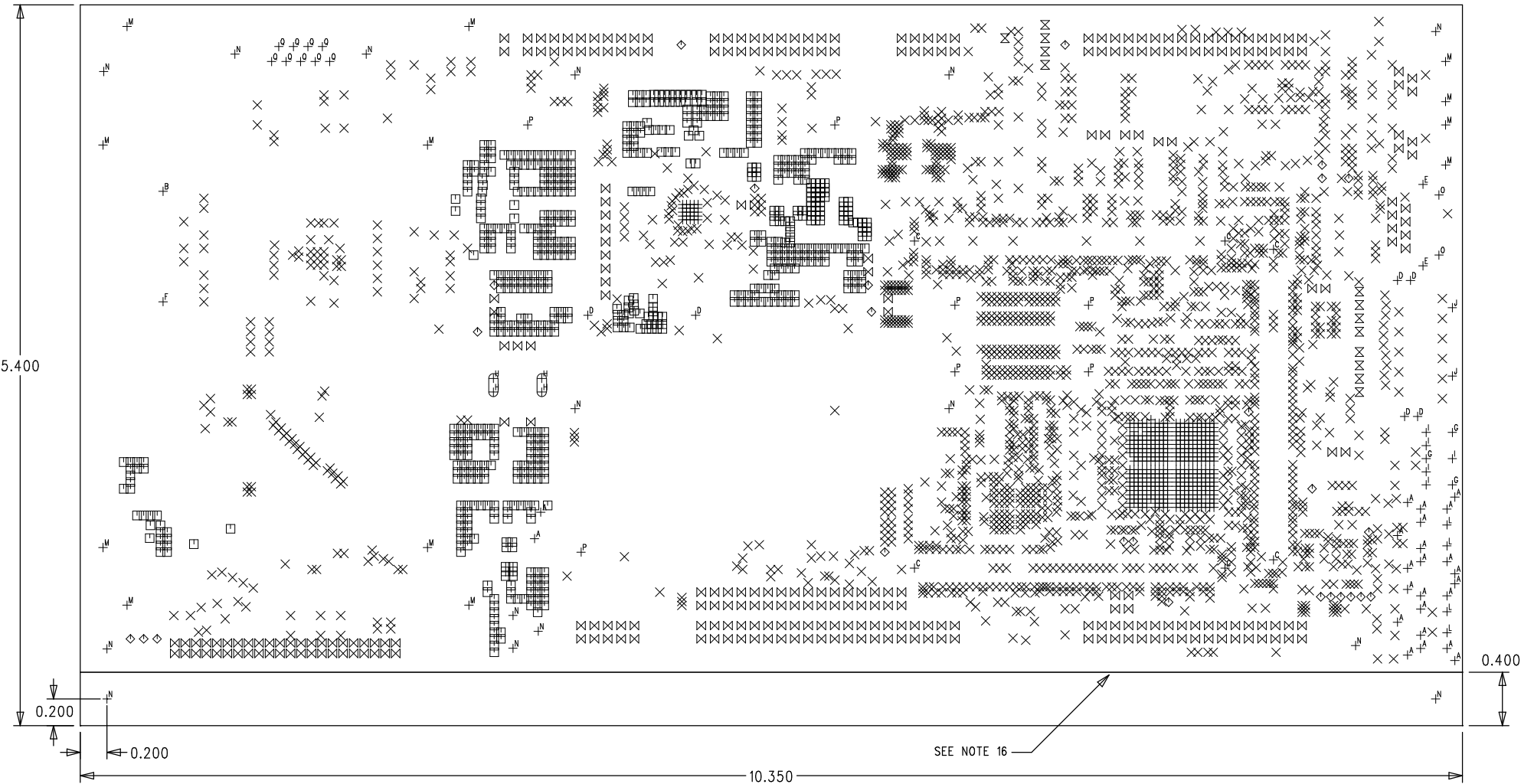



REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
1.0	NEW RELEASE	C.C.D.	12/22/06	
1.1	REFER TO ECO2007-012	C.C.D.	03/22/07	
1.2	REFER TO ECO2007-032	C.C.D.	05/08/07	
1.3	REFER TO ECO2007-048	C.C.D.	06/27/07	
1.4	REFER TO ECO2007-111	C.C.D.	12/05/07	

- UNLESS OTHERWISE SPECIFIED
- BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.
 - MATERIAL: POLYCLAD FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SQFT CU INNER LAYERS 1/2 OZ/SQFT CU FINISHED .062 (.050 MIN .070 MAX SEE DETAIL). VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
 - PLATING: ADDITIONAL CU PLATING 1 OZ/SQFT
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS.
WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
 - FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.
 - SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.
 - SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
 - ARTWORK: MINIMUM FEATURE SIZE = 0.00492
MINIMUM AIR GAP = 0.00449
 - ALL DIMENSIONS ARE IN INCHES.
 - CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE OF 60 OHMS +/-10% (SINGLE ENDED) ON ALL .005" LINE WIDTHS. ALL .007" LINE WIDTHS TO BE 50 OHMS SINGLE ENDED AND 100 OHMS DIFFERENTIAL +/-10%. ALL .0079" LINE WIDTHS TO BE 45 OHMS SINGLE ENDED AND 90 OHMS DIFFERENTIAL +/-10%.
 - DO NOT ADD NON-FUNCTIONAL COPPER THEIVING ON OPEN AREAS OF OUTER LAYERS. THEIVING IS ALLOWED ON INNER LAYERS, UNLESS OTHERWISE SPECIFIED.
 - VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES.
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
 - VIA HOLES (.006, .010, .012, & .014) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
 - TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
 - REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 3, 4, 7, AND 8 IS ACCEPTABLE.
 - USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
 - V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
 - BUILD AS 1-UP PCB.
 - THE FOLLOWING NETS ARE INTENTIONALLY SHORTED AND RESULT IN IPC NETLIST ERRORS:
AT W1 : GND & AGND (LAYERS 2 & 6)
AT W2 : GND & PGND (LAYERS 1 & 10)
AT W3 : GND & AGND2 (LAYERS 1 & 10)
AT W4 : GND & DGND2 (LAYERS 1 & 10)



SIZE	QTY	SYM	PLATED	TOL
0.006	415	+	YES	+ .003/- .006
0.01	2099	X	YES	+ .003/- .010
0.014	674	□	YES	+ .003/- .014
0.028	26	◇	YES	+/- .0003
0.032	13	⊗	YES	+/- .0003
0.038	298	⊗	YES	+/- .0003
0.042	9	⊕	YES	+/- .0003
0.043	24	⊕	YES	+/- .0003
0.044	1	⊕ ^B	NO	+/- .0003
0.053	6	⊕ ^E	NO	+/- .0003
0.055	6	⊕ ^D	YES	+/- .0003
0.063	2	⊕ ^E	YES	+/- .0003
0.063	1	⊕ ^E	NO	+/- .0003
0.067	3	⊕ ^E	NO	+/- .0003
0.071	5	⊕ ^E	YES	+/- .0003
0.071 x 0.173	2	⊕ ^D	YES	+/- .0003
0.09	2	⊕ ^E	NO	+/- .0003
0.117	4	⊕ ^E	NO	+/- .0003
0.125	15	⊕ ^D	YES	+/- .0003
0.125	12	⊕ ^D	NO	+/- .0003
0.128	2	⊕ ^D	NO	+/- .0003
0.167	7	⊕ ^E	YES	+/- .0005

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 20 Cotton Road Nashua, New Hampshire 03063 (603) 883-2430 FAX (603) 882-2655	
	APPROVALS	DATE		
MATERIAL SEE NOTES	DRAWN C.C.D.	12/05/07	FABRICATION DRAWING ADSP-BF548 EZ-KIT LITE	
	CHECKED			
FINISH SEE NOTES	ENGINEERING		SIZE B	REV. 1.4
	QUALITY		DWG. NO. A0206-2006-REF	
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1	SHEET 1 OF 1